

# **MOSFET** - P-Channel, QFET

# -200 V, -5.2 A, 690 mΩ

# FQPF7P20

#### **Description**

This P-Channel enhancement mode power MOSFET is produced using **onsemi**'s proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

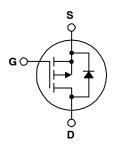
#### **Features**

- -5.2 A, -200 V,  $R_{DS(on)} = 690 \text{ m}\Omega$  (Max.) @  $V_{GS} = -10 \text{ V}$ , ID = -2.6 A
- Low Gate Charge (Typ. 19 nC)
- Low C<sub>rss</sub> (Typ. 25 pF)
- 100% Avalanche Tested

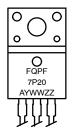


TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT

#### **N-CHANNEL MOSFET**



#### **MARKING DIAGRAM**



FQPF7P20

= Specific Device Code

YWW

= Assembly Location= Date Code (Year & Week)

ZZ

1

= Assembly Lot

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

# **ABSOLUTE MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter		Rating	Unit
V <sub>DSS</sub>	Drain-Source Voltage		-200	V
I <sub>D</sub>	Prain Current – Continuous (T <sub>C</sub> = 25°C) – Continuous (T <sub>C</sub> = 100°C)		-5.2 -3.3	A A
I <sub>DM</sub>	Drain Current	- Pulsed (Note 1)	-20.8	Α
V <sub>GSS</sub>	Gate-Source Voltage		±30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		570	mJ
I <sub>AR</sub>	Avalanche Current (Note 1)		-5.2	Α
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		4.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		-5.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>C</sub> = 25°C) – Derate Above 25°C		45 0.36	W W/°C
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

# THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W

# **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
OFF CHARACTERISTICS							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-200	_	_	V	
$\Delta BV_{DSS} / \Delta T_{J}$	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C	-	-0.1	-	V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -200 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -160 \text{ V}, T_C = 125^{\circ}\text{C}$	- -	- -	-1 -10	μ <b>Α</b> μ <b>Α</b>	
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$	-	_	-100	nA	
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0V	-	-	100	nA	
ON CHARA	ON CHARACTERISTICS						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250 \mu A$	-3.0	_	-5.0	V	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	$V_{GS} = -10 \text{ V}, I_D = -2.6 \text{ A}$	-	0.54	0.69	Ω	
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = -40 \text{ V}, I_D = -2.6 \text{ A}$	-	3.5	_	S	
DYNAMIC CHARACTERISTICS							
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	-	590	770	pF	
C <sub>oss</sub>	Output Capacitance	1	-	140	180	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance	]	-	25	35	pF	

# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)(continued)

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
SWITCHIN	G CHARACTERISTICS		•			
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -100 \text{ V}, I_D = -7.3 \text{ A},$	-	15	40	ns
t <sub>r</sub>	Turn-On Rise Time	$R_G = 25 \Omega \text{ (Note 4)}$	-	110	230	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	30	70	ns
t <sub>f</sub>	Turn-Off Fall Time		-	42	90	ns
Qg	Total Gate Charge	$V_{DS} = -160 \text{ V}, I_D = -7.3 \text{ A},$	-	19	25	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = -10 V (Note 4)	-	4.6	_	nC
Q <sub>gd</sub>	Gate-Drain Charge		-	9.5	-	nC
RAIN-SC	DURCE DIODE CHARACTERISTICS AND N	NAXIMUM RATINGS				
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		-	-	-5.2	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		-	-	-20.8	Α
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = -5.2 \text{ A}$	-	-	-5.0	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = -7.3 \text{ A,}$ $dI_{F}/dt = 100 \text{ A/}\mu\text{s}$	-	180	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		_	1.07	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2. L = 31.5 mH,  $I_{AS} = -5.2$  A,  $V_{DD} = -50$  V,  $R_{G} = 25$   $\Omega$ , starting  $T_{J} = 25^{\circ}$ C.

3.  $I_{SD} \le -7.3$  A, di/dt  $\le 300$  A/ $\mu$ s,  $V_{DD} \le BV_{DSS}$ , starting  $T_{J} = 25^{\circ}$ C.

4. Essentially independent of operating temperature.

## **TYPICAL CHARACTERISTICS**

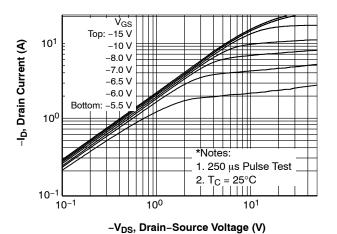


Figure 1. On-Region Characteristics

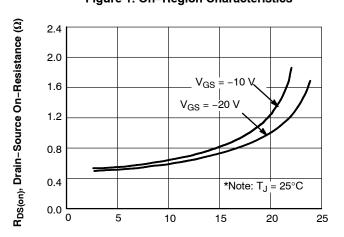


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

-I<sub>D</sub>, Drain Current (A)

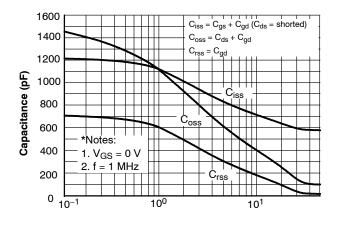
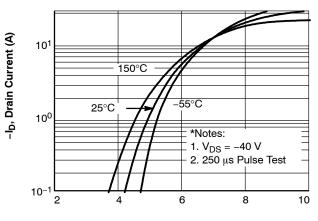


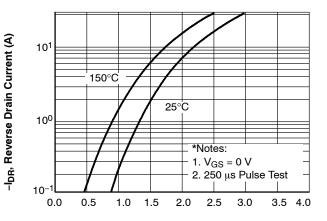
Figure 5. Capacitance Characteristics

-V<sub>DS</sub>, Drain-Source Voltage (V)



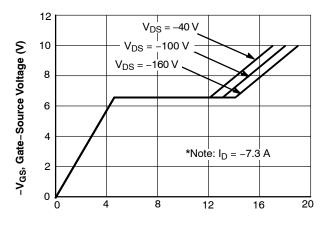
-V<sub>GS</sub>, Gate-Source Voltage (V)

Figure 2. Transfer Characteristics



-V<sub>SD</sub>, Source-Drain Voltage (V)

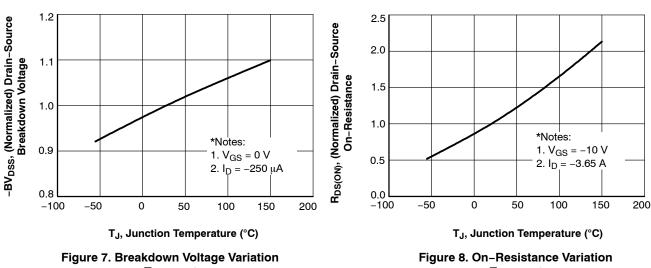
Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



Q<sub>G</sub>, Total Gate Charge (nC)

Figure 6. Gate Charge Characteristics

# TYPICAL CHARACTERISTICS (continued)



-I<sub>D</sub>, Drain Current (A)

vs. Temperature

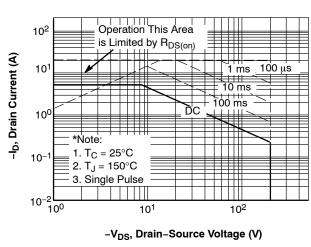


Figure 9. Maximum Safe Operating Area

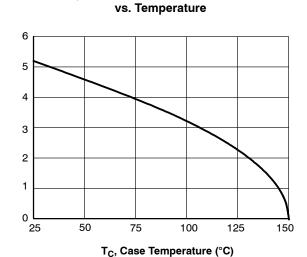
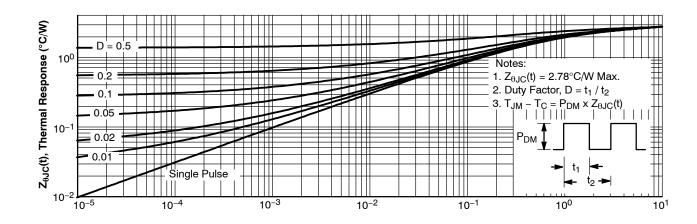


Figure 10. Maximum Drain Current vs. Case **Temperature** 



t<sub>1</sub>, Square Wave Pulse Duration (s)

Figure 11. Transient Thermal Response Curve

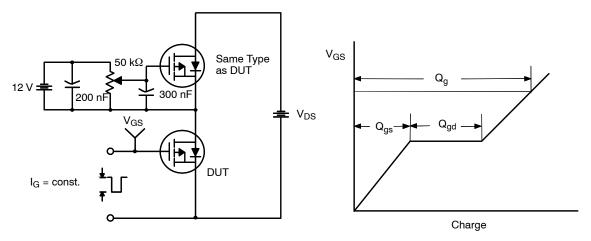


Figure 12. Gate Charge Test Circuit & Waveform

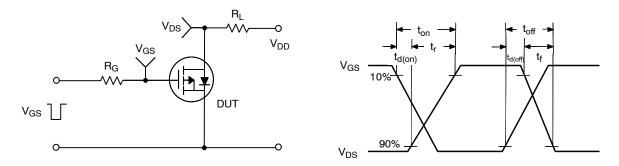


Figure 13. Resistive Switching Test Circuit & Waveforms

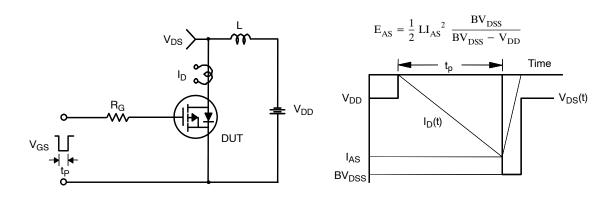
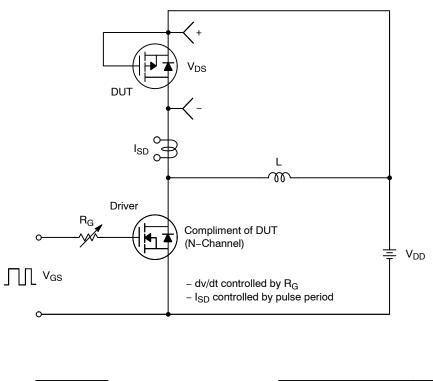
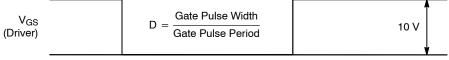
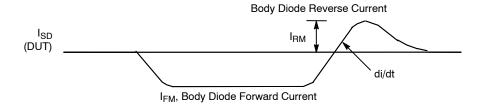


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms







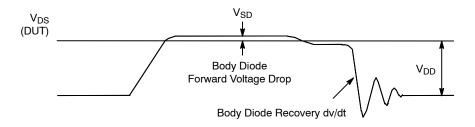
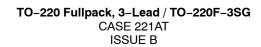


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

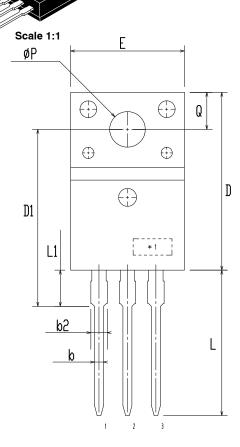
# PACKAGE MARKING AND ORDERING INFORMATION

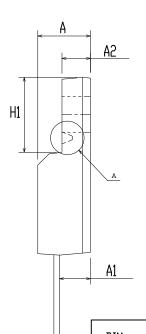
Part Number	Top Mark	Package	Shipping
FQPF7P20	FQPF7P20	TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT	1,000 Units / Tube

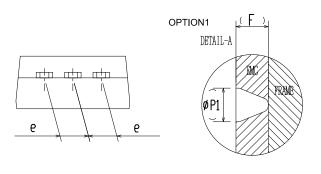




**DATE 19 JAN 2021** 







DIM	LITE	LIIII I LIVO		
ויונע	MIN	NDM	MAX	
Α	4.50	4.70	4.90	
A1	2.56	2.76	2.96	
A2	2.34	2.54	2.74	
b	0.70	0.80	0.90	
b2	~	2	1.47	
С	0.45	0.50	0.60	
D	15.67	15.87	16.07	
D1	15.60	15.80	16.00	
E	9.96	10.16	10.36	
е	2.34	2.54	2.74	
F	~	0.84	~	
H1	6.48	6.68	6.88	
L	12.78	12.98	13.18	
L1	3.03	3.23	3.43	
øΡ	2.98	3.18	3.38	
ø P1	~	1.00	~	
Q	3.20	3.30	3.40	

MILL IMITERS

## NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.

C

C. OPTION 1 - WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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DESCRIPTION:	TO-220 FULLPACK, 3-LEAD / TO-220F-3SG		PAGE 1 OF 1	

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